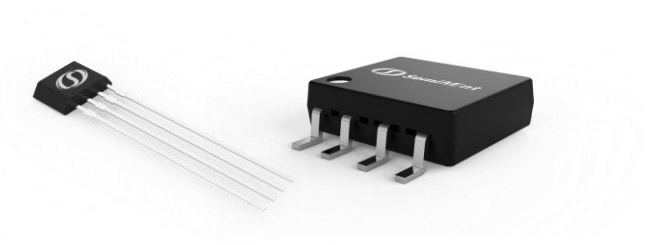
Dual Channel Hall-effect Switch with Quadrature A/B and Direction Outputs

FEATURES

- Precisely aligned dual Hall elements
- Logic output signals for quadrature A/B outputs
- Logic output signals for direction
- Superior temperature stability and industry-leading
  - jitter performance through use of advanced chopper
  - stabilization topology
- High sensitivity (B_{OP} and B_{RP})
- Supports a wide voltage range: 3.0 to 24 V
- Solid-state reliability
- Small package sizes

APPLICATIONS

- Magnetic encoding
- Rotating shaft monitoring
- Garage door openers
- Power sliding doors
- Sunroofs motor



DESCRIPTION

The SC2526 is a dual-channel Hall-effect sensor IC ideal for use in speed and direction sensing applications incorporating encode ring-magnet targets. The SC2526 provides various output signals that indicate speed and direction of target rotations. The Hall elements are both photos lithographically aligned to better than 1um. Maintaining accurate displacement between the two active Hall elements eliminates the major manufacturing hurdle encountered in fine-pitch detection applications. The SC2526 is a sensitive, temperature-stable magnetic device ideal for use in harsh automotive and industrial environments.

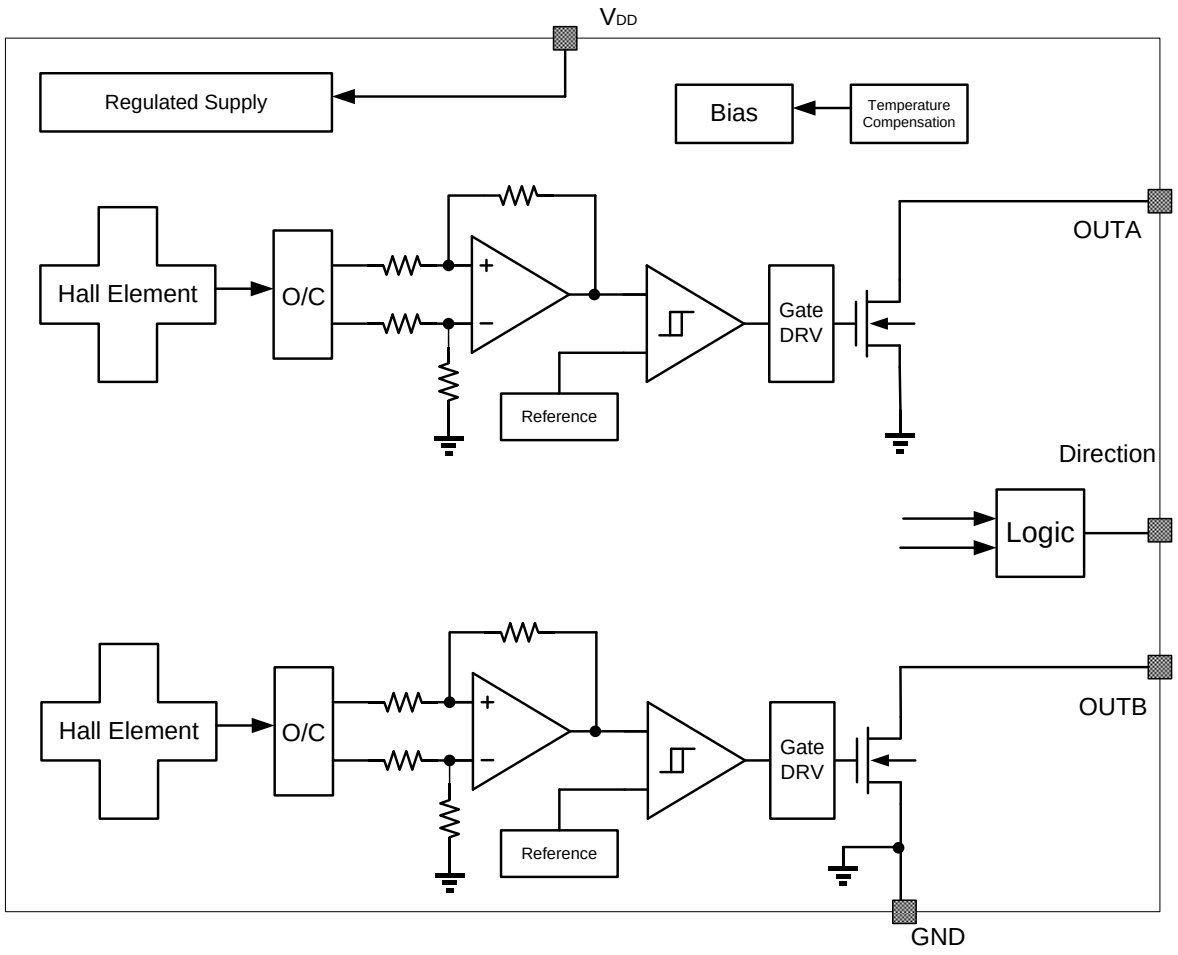
The Hall elements of the SC2526 are spaced 1.4mm apart, which provides excellent speed and direction information for small-geometry targets. Extremely low-drift amplifiers guarantee symmetry between the switches to maintain signal quadrature. An on-chip regulator allows the use of this device over a wide operating voltage range of 3.0 to 24V

The digital outputs are out of phase so that the outputs are in quadrature when interfaced with the proper ring magnet design. For the direction signal to be updated, a quadrature relationship must be maintained.

The SC2526 is available in a 4-pin SIP and a plastic 8-pin SOIC surface mount package. Both packages are lead (Pb) free, with 100% matte tin lead frame plating.

CONTENTS

BLOCK DIAGRAM

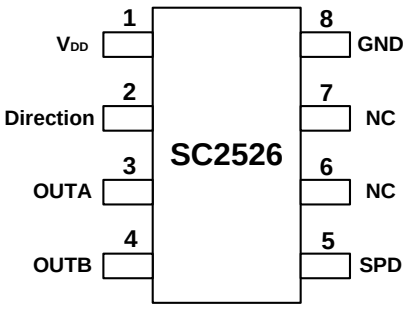


ORDERING INFORMATION

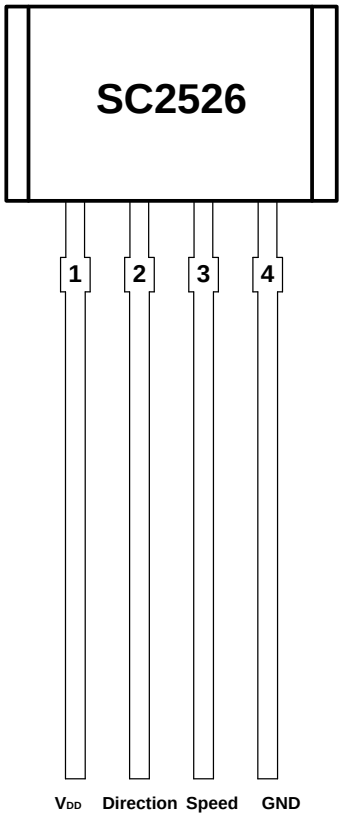
Part Number	Packing	Mounting	Ambient, T_A	B_{OP}(Typ.)	B_{RP}(Typ.)
SC2526VB	Bulk, 500 pieces/bag	4-pin SIP	-40℃ to 150℃	+10mT	-10mT
SC2526DC	Reel, 3000pieces/reel	8-pin SOIC			

TERMINAL CONFIGURATION

SOP8
DC Package
(Top View)



4-Terminal SIP
VB Package
(Top View)



Terminal			Type	Description
Name	Number			
	DC	VB		
V_{DD}	1	1	Power	3.0V ~ 24 V power supply
Direction	2	2	Output	Direction output. The open drain requires a pull-up resistor
OUTA	3	3	Output	A channel peed output. The open drain requires a pull-up resistor
OUTB	4	--	Output	B channel peed output. The open drain requires a pull-up resistor
Speed	5	--	Output	A XOR B output
NC	6	--	NC	--
NC	7	--	NC	--
GND	8	4	Ground	Ground terminal

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range

Parameter	Symbol	Min.	Max.	Units
Power supply voltage	V_{DD}	-0.5	28	V
Output terminal voltage	V_{OUT}	-0.5	28	V
Output terminal current sink	I_{SINK}	0	25	mA
Operating ambient temperature	T_A	-40	150	℃
Maximum junction temperature	T_J	-55	165	℃
Storage temperature	T_{STG}	-65	175	℃

Note: Stresses above those listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD PROTECTION

Human Body Model (HBM) tests according to: standard AEC-Q100-002 HBM

Parameter	Symbol	Min.	Max.	Units
ESD-Protection	V_{ESD}	-4	4	kV

THERMAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	Rating	Units
$R_{\theta JA}$	VB Package thermal resistance	Single-layer PCB, with copper limited to solder pads	177	℃/W
$R_{\theta JA}$	BU Package thermal resistance	Single-layer PCB, with copper limited to solder pads	140	℃/W

OPERATING CHARACTERISTICS

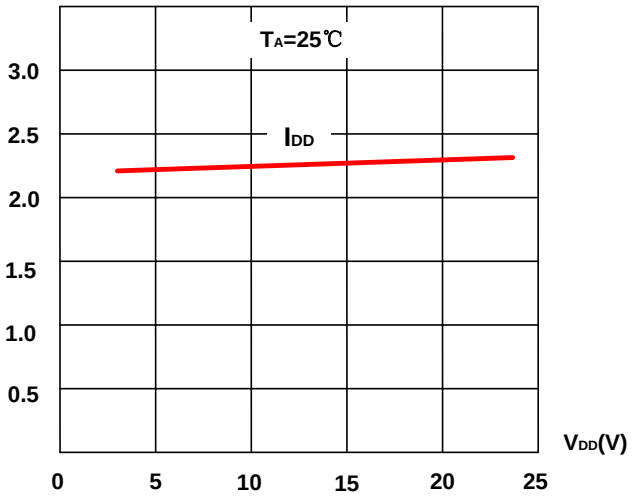
over operating free-air temperature range (V_{DD} = 5.0V, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{DD}	Operating voltage	$T_J < T_{J(Max.)}$	3.0	--	24	V
I_{DD}	Operating supply current	V_{DD}=2.8 to 24 V	1.0	--	3.5	mA
t_{on}	Power-on time		--	35	50	μS
I_{QL}	Off-state leakage current	Output Hi-Z	--	--	1	μA
$R_{DS(on)}$	FET on-resistance	V_{DD}=5V, I_O=10mA, T_A=25℃	--	20	--	Ω
t_d	Output delay time	B=B_{RP} to B_{OP}	--	13	25	μS
t_r	Output rise time	R1=1Kohm Co=50pF	--	--	0.8	μS
t_f	Output fall time	R1=1Kohm Co=50pF	--	--	0.8	μS
Magnetic Characteristics						
f_{BW}	Bandwidth		40	--	--	kHz
B_{OP}	Operated point	VB Package	7.5	10.0	14.5	mT
B_{RP}	Release point		-14.5	-10.0	-7.5	mT
B_{HYS}	Hysteresis		--	20.0	--	mT
B_O	Magnetic offset	B_O=(B_{OP}+B_{RP})/2	--	0	--	mT

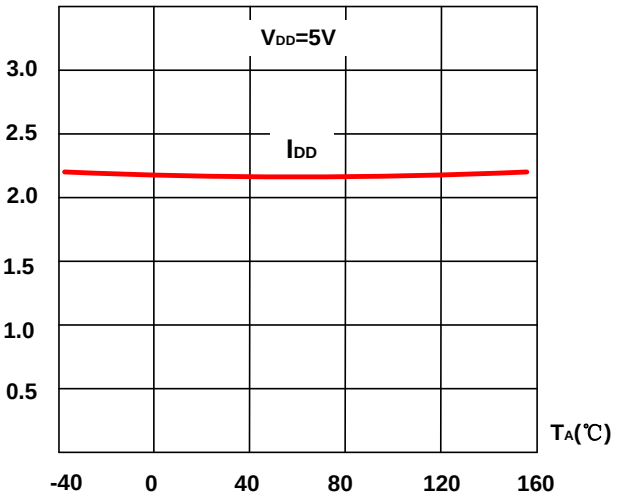
1mT=10Gs

TYPICAL CHARACTERISTICS

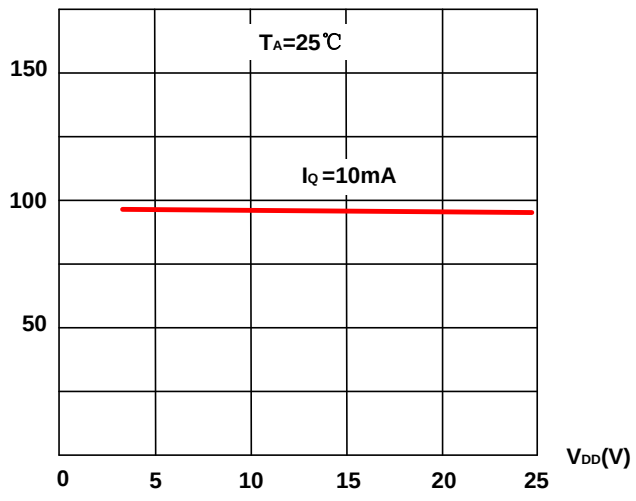
Quiescent Current versus Supply Voltage



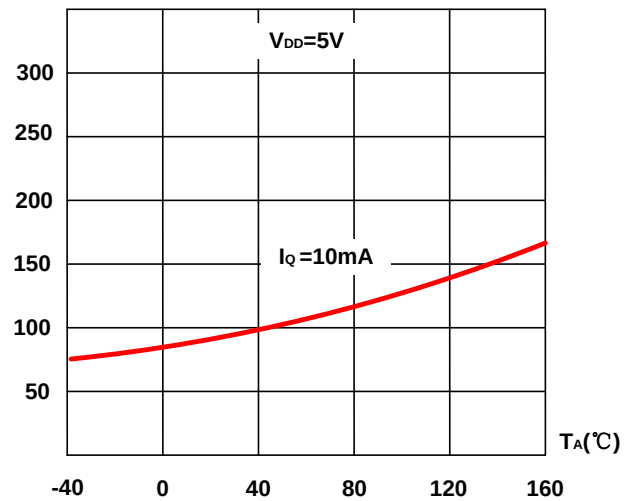
Quiescent Current versus Temperature



Saturation Voltage versus Supply Voltage

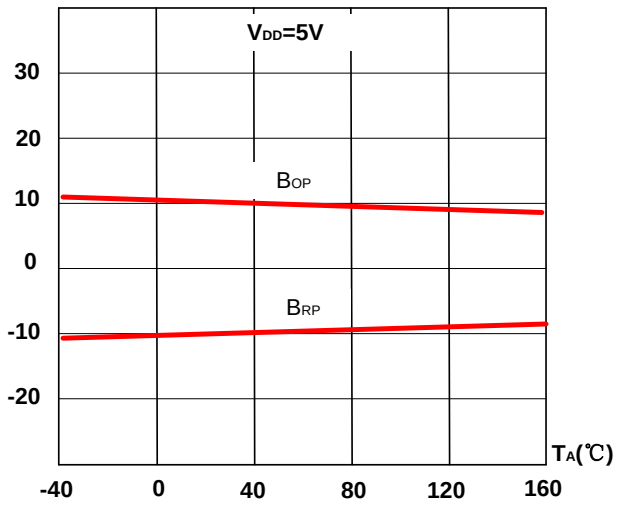


Saturation Voltage versus Temperature

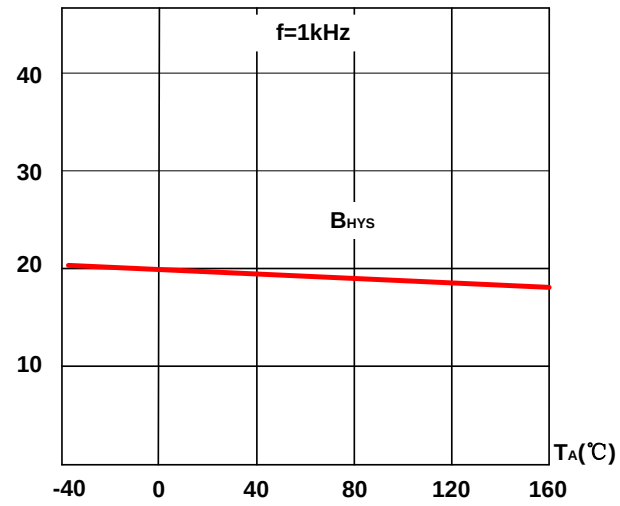


TYPICAL CHARACTERISTICS (continued)

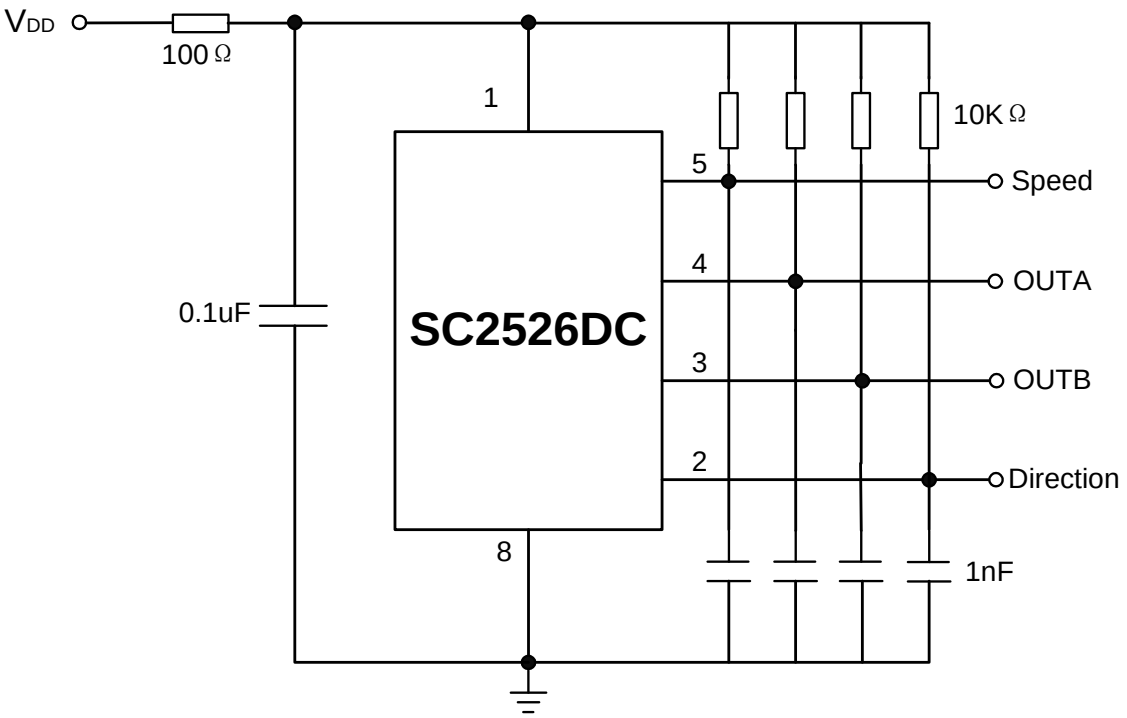
B_{OP} and B_{RP} versus Temperature

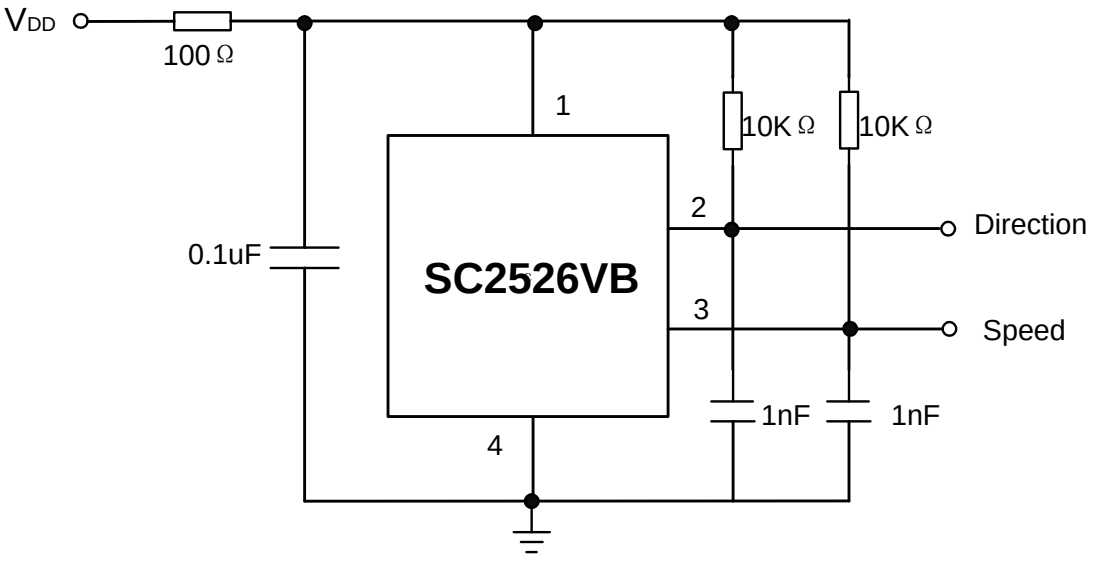


B_{HYS}(mT) Hysteresis versus Temperature

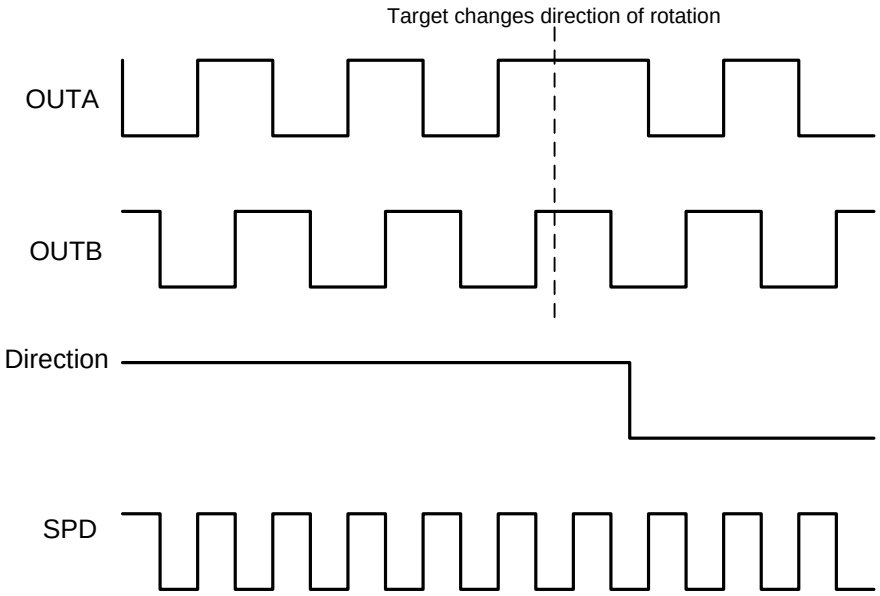


TYPICAL APPLICATION

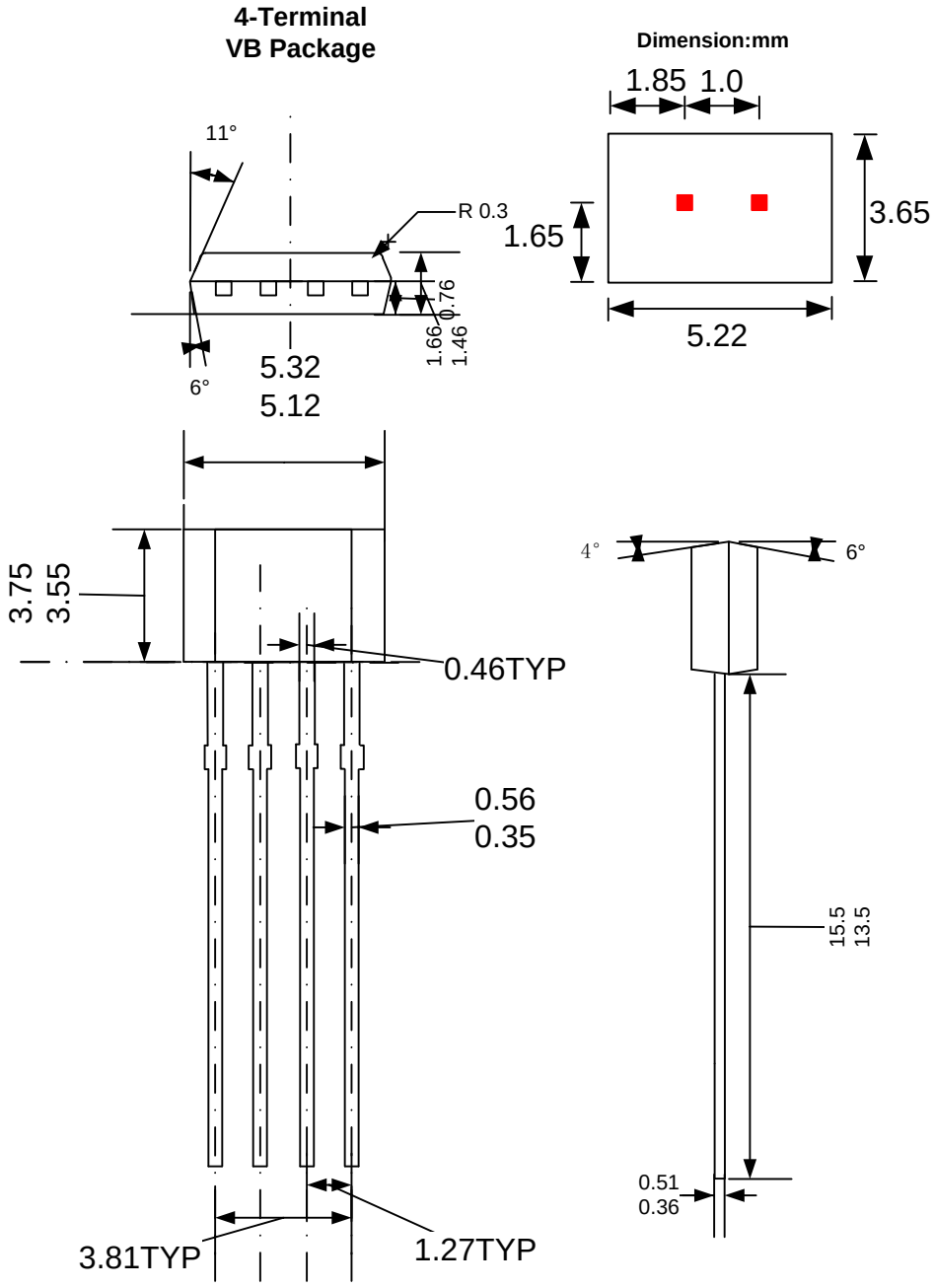




TYPICAL OUTPUT WAVEFORM



PACKAGE INFORMATION (VB)

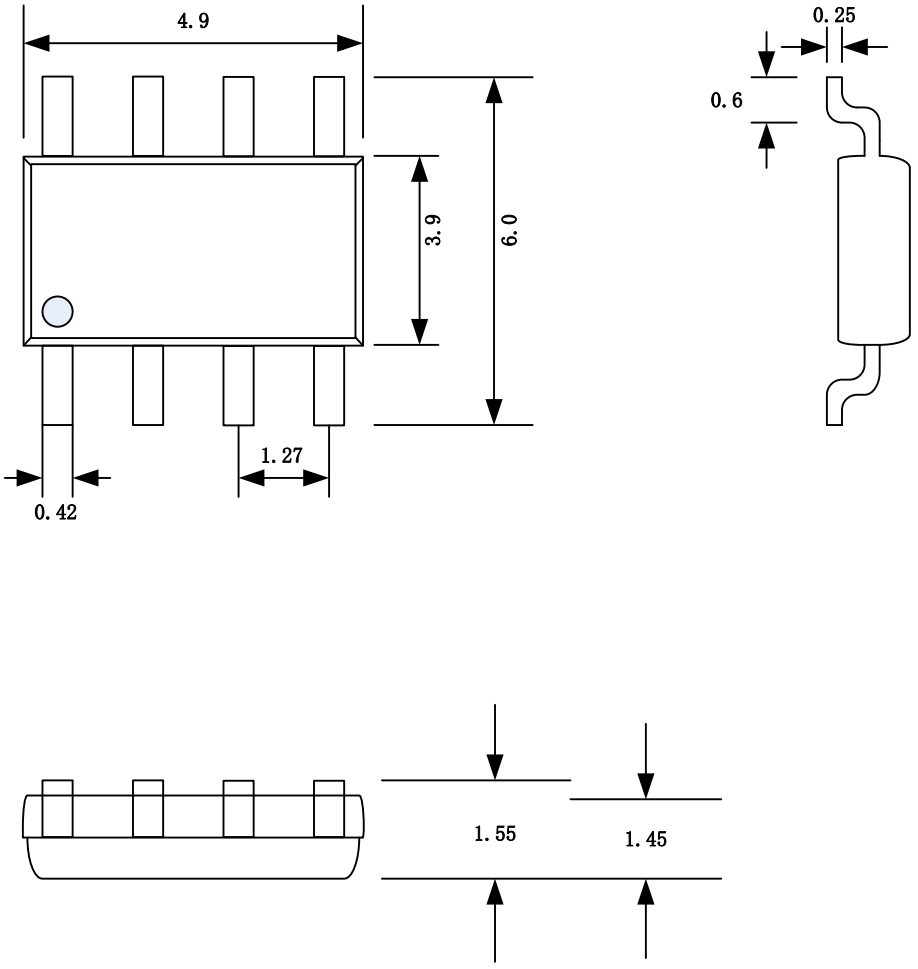


Notes:

1. *Exact body and lead configuration at vendor's option within limits shown.*
2. *Height does not include mold gate flash.*

Where no tolerance is specified, dimension is nominal.

PACKAGE INFORMATION (DC)



Notes:

1. Exact body and lead configuration at vendor's option within limits shown.
2. Height does not include mold gate flash.

Where no tolerance is specified, dimension is nominal.

REVISON HISTORY

Revision	Date	Description
Rev0.1	2017-03-02	Preliminary datasheet
Rev2.3	2018-09-02	The final revision of old datasheet
RevA/1.0	2020-11-19	Unified datasheet format